

What is claimed is:

1. An embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity  
5 of not higher than  $85 \text{ Pa} \cdot \text{s}$  in a shear rate of  $8.4 \text{ s}^{-1}$  after allowing to stand for 24 hours at  $25^\circ\text{C} \pm 1^\circ\text{C}$ .

2. The embedding resin according to claim 1, wherein the acid anhydride curing agent has a viscosity at  $25^\circ\text{C} \pm 1^\circ\text{C}$   
10 of not higher than  $170 \text{ mPa} \cdot \text{s}$ .

3. The embedding resin according to claim 1, which contains the filler in an amount of from 51% by weight to 74% by weight.  
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4. The embedding resin according to claim 1, wherein the filler contains at least one inorganic filler.

5. A wiring substrate comprising: an insulating  
20 substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin according to claim 1, wherein the at least one electronic part is embedded with the embedding resin.

6. A wiring substrate comprising: a core substrate;  
and a build-up layer provided on at least one side of the core  
substrate and formed by alternately laminating an insulating  
layer and a wiring layer, wherein at least one of the core  
5 substrate and the building-up layer has an opening  
penetrating therethrough, and an electronic part is disposed  
in the opening and embedded with an embedding resin according  
to claim 1.